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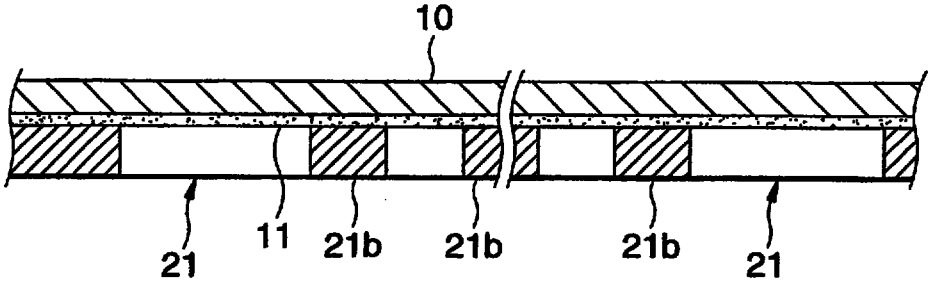
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(54) Title: LEAD FRAME LAMINATE AND METHOD FOR MANUFACTURING SEMICONDUCTOR PARTS



(57) Abstract: A lead frame laminate for use in manufacturing semiconductor parts is provided. A lead frame has an opening and a copper terminal portions formed in the opening. A base material film covers at least the opening and the terminal portions, and laminated on the lead frame through an adhesive layer. The adhesive layer contains a silicone binder and an oxidation inhibitor.

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